

Part Number: XZM2DG67S

4.0x4.0mm RIGHT ANGLE SURFACE MOUNT LED LAMP

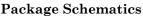
Features

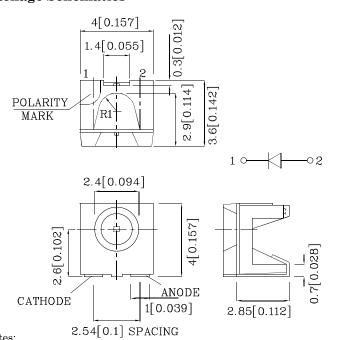
- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 500pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- \bullet RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES





Notes: 2.34[0.1] SPACING 1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

3. Specifications are subject to change without notice.

M2DG Absolute Maximum Ratings Unit (T_A=25°C) (InGaN) V **Reverse Voltage** V_{R} $\mathbf{5}$ Forward Current \mathbf{I}_{F} 30 mА Forward Current (Peak) 1/10 Duty Cycle 100 i_{FS} mА 0.1ms Pulse Width 120 Power Dissipation \mathbf{P}_{D} mW T_A $-40 \sim +85$ **Operating Temperature** °C Storage Temperature Tstg $-40 \sim +85$ Electrostatic Discharge Threshold 450V (HBM)

Operating Characteristics (T _A =25°C)		M2DG (InGaN)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.2	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V	
Reverse Current (Max.) (V _R =5V)	I_R	50	uA	
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	520*	nm	
Wavelength of Dominant EmissionCIE127-2007*(Typ.) (I _F =20mA)	λD	525*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	35	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	$_{\rm pF}$	

Part Number	Emitting Color	Emitting Material	Lens-color	CIE12 (I _F =2	s Intensity 7-2007* 20mA) acd	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZM2DG67S	Green	InGaN	Water Clear	700*	1195*	520*	120°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

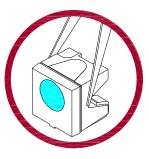
Feb 24,2014



Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



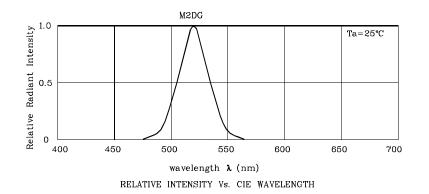


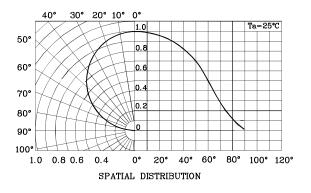
3. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.



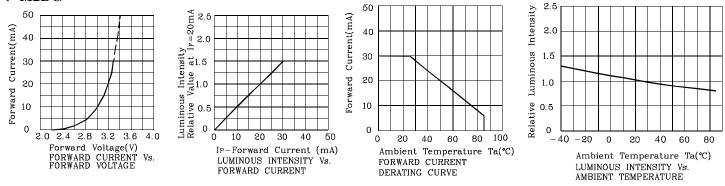
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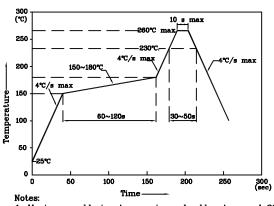






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



- 1. Maximum soldering temperature should not exceed 260°C 2. Recommended reflow temperature: 145°C-260°C
- 2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during
- high temperatures conditions

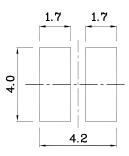


✤ The device has a single mounting surface. The device must be mounted according to the specifications.

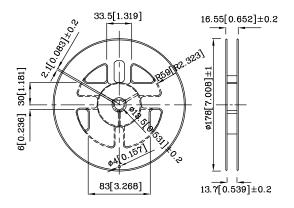
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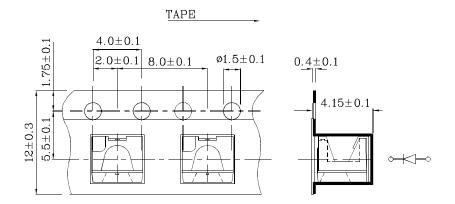
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

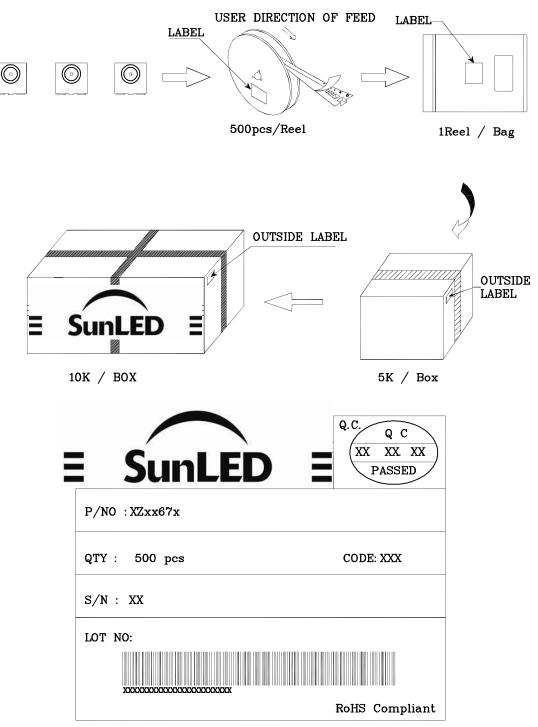
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at <u>http://www.SunLEDusa.com/TechnicalNotes.asp</u>